

TTM Technologies, Inc. Announces Upcoming Conference Participation

May 5, 2016 2:18 PM ET

for immediate release

Costa Mesa, CA - May 5, 2016 - TTM Technologies, Inc. (NASDAQ:TTMI), a leading global printed circuit board (PCB) manufacturer, today announced that members of its management team will present at the following investor conferences:

- The Stifel Technology, Internet & Media Conference in San Francisco at The Fairmont Hotel on Monday, June 6, 2016 at 4:45 PM Pacific Time; and
- The Barclays High Yield Bond & Syndicated Loan Conference in Colorado Springs at The Broadmoor on Thursday, June 9, 2016 at 10:10 AM Mountain Time.

The Company is also hosting an Analyst Day in New York at The Westin New York Grand Central on Tuesday, May 17, 2016 from 10:00 AM Eastern Time to 1:00 PM Eastern Time.

All presentations will be webcast live on the company's website, www.ttm.com, and a replay will be accessible for a limited time following the events.

About TTM

TTM Technologies, Inc. is a leading global printed circuit board manufacturer, focusing on quick-turn and technologically advanced PCBs, backplane assemblies and electro-mechanical solutions. TTM stands for time-to-market, representing how TTM's time-critical, one-stop manufacturing services enable customers to shorten the time required to develop new products and bring them to market. Additional information can be found at www.ttm.com.

Company

TTM Technologies
(ticker: TTMI, exchange: NASDAQ)

Release Info

News Release:
5/5/2016

Contact

Sameer Desai
Senior Director, Corporate
Development & Investor Relations
sameer.desai@ttmtech.com
714-327-3050